

tentative

Туре	Ag [*] Aİ [*]	V _{DRM} / V _{RRM}	V _{DSM} /V _{RSM} [∀]	I_{Т(AV)} [A]	Chip Size [mm] x [mm]	Package Options	•
CWP 55-	16 🗹 🗹	1600	1700	90	12.30 12.3	sawn on foil vunsawn wafer vin waffle pack vin	
	*Frontside options					*Please contact IXYS chip sales	

Mechanical Parameters

Area active Area total Wafer size Ø Thickness Material Max. possible chips per wafer Passivation front side Metallization top side top side Recom. wire bonds (AI) Cathode * = Stitchbonds Number / Ø [µm] 12* / 500 Metallization backside solderable (only): Ti / Ni / Ag * Reject Ink Dot Size Recom. Storage Environment sawn on foil unsawn wafer in waffle pack T_{stq}

cm² 0.89 1.51 cm² 150 mm 380 μm Si 89 Glassivation solderable: Ti / Ni / Ag * bondable: ΑI Gate 1 / 500

in org. container, in dry nitrogen < 6 month in org. container, in dry nitrogen < 2 year <2 year in org. container, in dry nitrogen -40... 40 °C

Ø 0.4-1.0 mm

Features

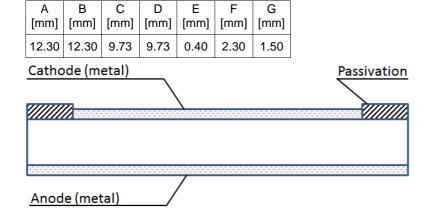
- planar design (non-mesa)
- ultra rugged for easy assembly (flat backside)
- excellent long term stability
- very low leakage current
- very low forward voltage drop

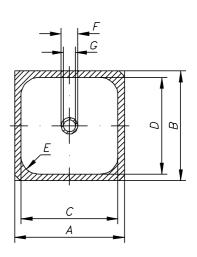
Applications

- DC motor control
- AC power control
- Softstrart AC motor controller
- Light, heat and temperature control
- Solid state relays
- Controlled rectifier circuits

*Sinterable top/bottom side on request

Dimensions





Thyristor Chip

tentative

	Ratings				
Symbol	Conditions	min.	typ.	max.	
I _R 1)	$V_D = Vr = Vrr$	$T_{VJ} = 25^{\circ}C$		0.1	m/
		$T_{V,I} = 150^{\circ}C$		20	m/
V ₇	I _T =200 A	$T_{VJ} = 25 ^{\circ}\text{C}$	1	1.29	\
		T _{V.I} = 150 °C		1.30	١
V_{T0} 1)	For power-loss	s calculations only		0.88	١
r ,	$T_{VJ} = 150 ^{\circ}\text{C}$		Y	1.90	mΩ
V _{G7}	$V_D = 6 V$	$T_{VJ} = 25^{\circ}C$	10	1.5	1
		$T_{VJ} = -40$ °C		1.6	١
I _{GT}	$V_D = 6 V$	$T_{VJ} = 25^{\circ}C$		95	m/
		$T_{VJ} = -40$ °C		200	m/
V_{GD}	$T_{VJ} = 150 ^{\circ}\text{C}$	$V = \frac{2}{3} V_{DRM}$		0.2	١
l _{gD}				10	m/
I <u>L</u>	t _p =10 μs	$T_{VJ} = 25^{\circ}C$ $I_{G} = 0.45 \text{ A}$ $di_{G}/dt = 0.45 \text{ A/}\mu\text{s}$		450	m/
I _H	R _{GK} = ∞	$T_{VJ} = 25^{\circ}C$ $V_{D} = 6 \text{ V}$		200	m/
t _{gd}	$V_D = \frac{1}{2} V_{DRM}$	T _{v1} = 25°C		2	μ
		$di_{G}/dt = 0.5 A/\mu$			
t_q		$I_{T} = 90 \text{ A}$ -di/dt = 10 A/ μ s		150	μ
		$dv/dt = 20 V/\mu s V_D = \frac{2}{3} V drm T_{V,I} = 125 °C$			•
(di/dt) _a	repetitive	I _T = 150 A		150	A/µs
	non repetitive	$I_T = 90$ A		500	A/µs
	$V = \frac{2}{3} V_{DRM}$	$T_{VJ} = 150 ^{\circ}\text{C}$ $di_{G}/dt = 0.45 A/\mu s$			
	$I_{G} = 0.45 \text{ A}$	$t_p = 200 \ \mu s$ $f = 50 \ Hz$			
(dv/dt) _{cr} 1)	T _{vJ} = 150 °C	$V_{DR} = \frac{2}{3} V_{DRM}$		1000	V/µs
	R _{GK} = ∞	method 1 (linear voltage rise)			
P _{GM}	T _{vJ} = 150 °C	$t_p = 30 \mu s$		10	V
		$t_p = 3E \mu s$		5	W
$P_{\scriptscriptstyle GAV}$				0.5	W
V _{RGM}				10	\
T _{VJ}		-40		150	°C
I _{T(AV)}	$T_{\rm C} = 100 ^{\circ}{\rm C}$	180° rect.		90	P
	$T_{VJ} = {}^{\circ}C$	180° sine		87	P
I _{TSM} *	$T_{VJ} = 45^{\circ}C$	t = 10 ms (50) Hz, sine		1900	A
	$V_R = 0 V$	t = 8.3 ms (60) Hz, sine		2000	P
		t = 10 ms (50) Hz, sine		1700	P
	$V_R = 0 V$	t = 8.3 ms (60) Hz, sine		1800	A
ft *		t = 10 ms (50) Hz, sine		18050	Α :
	$V_R = 0 V$		16600	Α :	
	T _{vJ} = 150 °C	·			
	$V_R = 0 V$	t = 8.3 ms (60) Hz, sine		13446	A s
R _{thJC} *	DC current		0.45		K/W

^{*} Data according to assembled product MCC 56

Data according to IEC 60747

tentative

Terms of Conditions and Usage

The data contained in this product data sheet is exclusively intended for technically trained staff. The user will have to evaluate the suitability of the product for the intended application and the completeness of the product data with respect to his application. The specifications of our components may not be considered as an assurance of component characteristics. Should you require product information in excess of the data given in this product data sheet or which concerns the specific application of our product, please contact the sales office, which is responsible for you. Due to technical requirements our product may contain dangerous substances. For any information on the types in question please contact the sales office/partner, which is responsible for you.

Should you intend to use the product in aviation applications, in health or life endangering or life support applications, please notify. For any such applications we urgently recommend

- to perform joint risk and quality assessments;
- the conclusion of quality agreements;
- to establish joint measures to ensure application specific product capabilities and notify that IXYS may delivery dependent on the realization of any such measures.